

# AN005u: IC Package / PCB Footprint Guidelines - QFN76

Document Revision V1.0 • 2022-Feb-07

**This application note is meant to be a practical guideline for a specific TRINAMIC IC package and its PCB footprint. The document covers package dimensions, example footprint and general information on PCB footprints.**

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### 3 Overview

This application note is meant to be a practical guideline for a specific TRINAMIC IC package and its PCB footprint. The document covers package dimensions, example footprint and general information on PCB footprints with their packaging as well.

## 4 QFN76 Package Details

### 4.1 QFN76

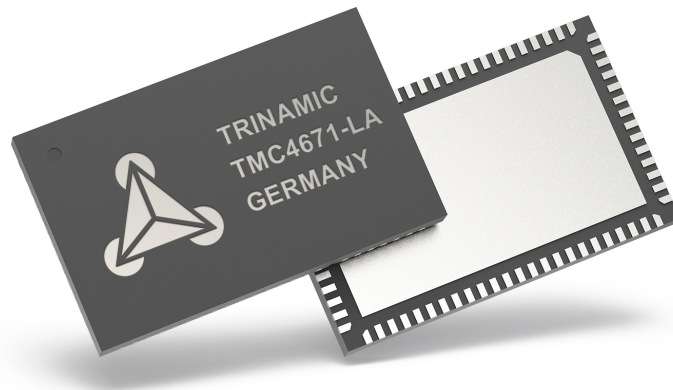


Figure 1: QFN76 3D example

## 4.2 Dimensions

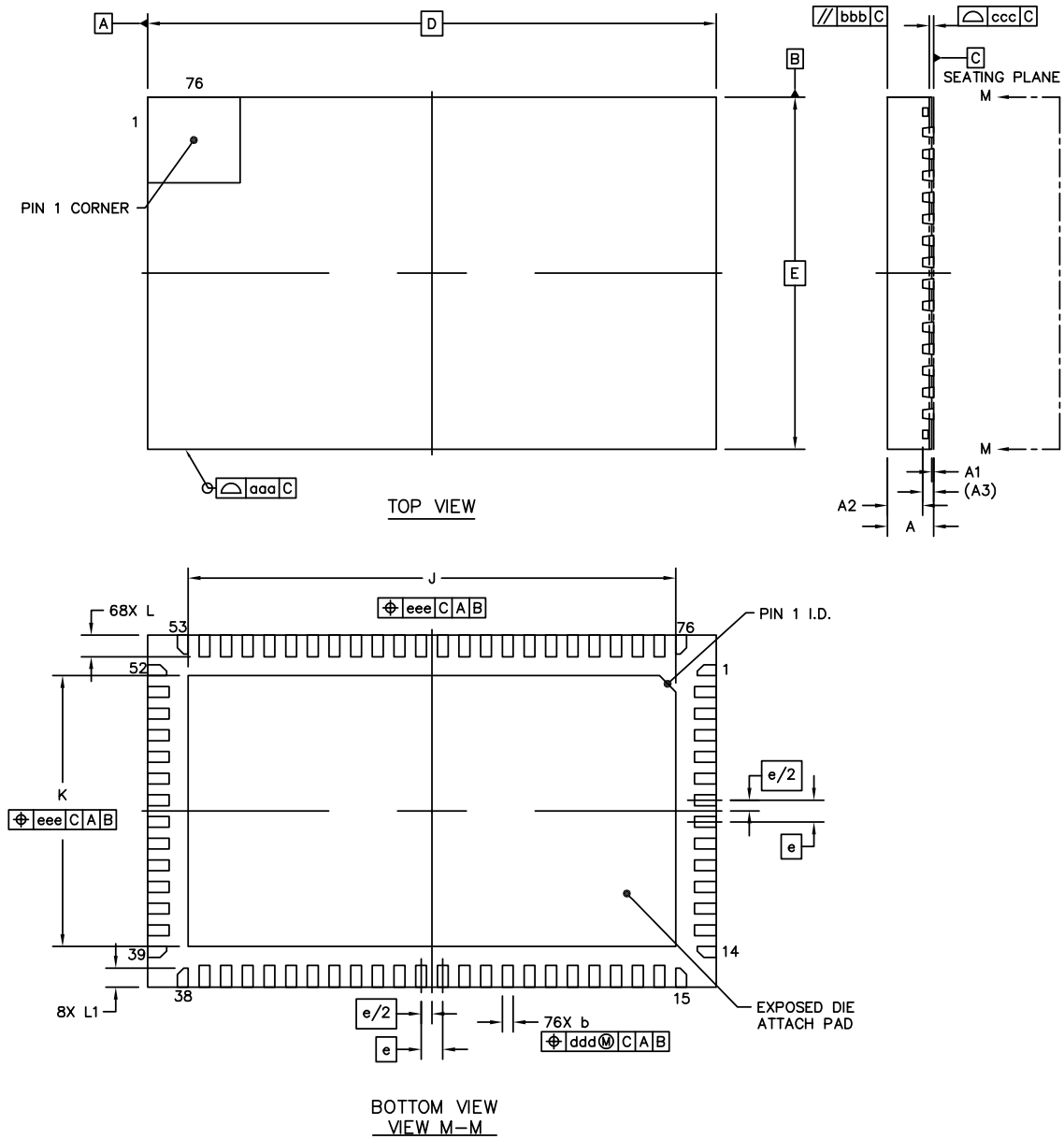


Figure 2: QFN76 package outline drawings

Table 1: QFN76 dimensions

Symbol	Dimensions in MILLIMETERS			Dimensions in INCHES		
	Min	Typ	Max	Min	Typ	Max
<b>A</b>	0.8	0.85	0.9	0.0315	0.0335	0.0354
<b>A1</b>	0	0.035	0.05	0	0.0014	0.002
<b>A2</b>	-	0.65	-	-	0.0256	-
<b>A3</b>	0.203 REF			0.0078 REF		
<b>b</b>	0.15	0.2	0.25	0.0059	0.00787	0.0098
<b>D</b>	10.5 BSC			0.4134 BSC		
<b>E</b>	6.5 BSC			0.2559 BSC		
<b>e</b>	0.4 BSC			0.0157 BSC		
<b>J</b>	8.9	9	9.1	0.3504	0.3543	0.3583
<b>K</b>	4.9	5	5.1	0.1929	0.1969	0.2008
<b>L</b>	0.35	0.4	0.45	0.0138	0.0157	0.0177
<b>L1</b>	0.3	0.35	0.4	0.0118	0.0138	0.0157

## 5 General PCB Footprint and Packaging Information Resources

These guidelines and information are proposals and suggestions as they are proven and work well with TRINAMIC modules. Some ICs are available in Tape & Reel and in IC trays.

### 5.1 QFN Packages

These are basic guidelines for Quad Flat No Leads Packages (QFNs). They are derived from the Technical Brief TB389 from Renesas (TB389).

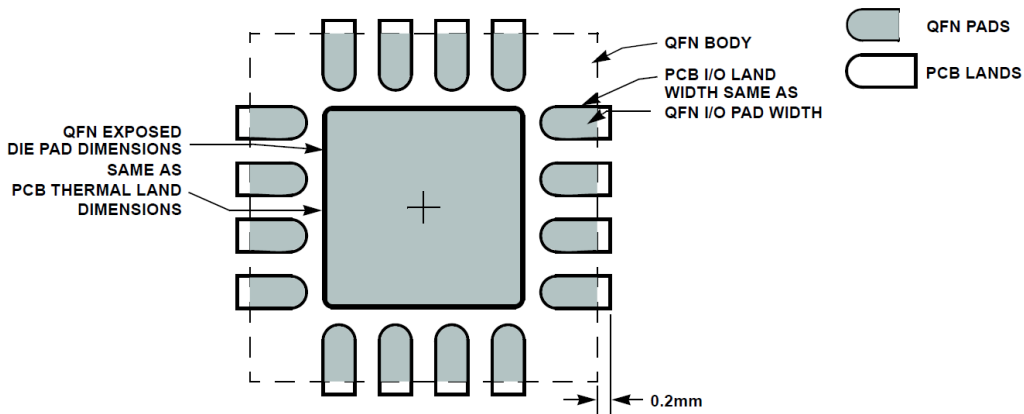


Figure 3: Board Layout of Soldered Pad for QFN Devices according to Renesas TB389



## 6 Disclaimer

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## 7 Revision History

*Table 2: Document Revision*

Version	Date	Author	Description
V1.00	11.02.2022	FV	V1.00 release version